

DT1446-04SO

4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

Product Summary

V _{BR (min)}	I _{PP (max)}	C _{T (typ)}
6V	4.7A	0.55pF

Description

The DT1446-04SO is a high performance device suitable for protecting four high speed I/Os and one V_{CC} . These devices are assembled in SOT26 package. They have high ESD surge capability and low capacitance.

Applications

 Typically Used for High Speed Ports such as USB 2.0, IEEE1394, HDMI, Laptop and Personal Computers, Flat Panel Displays, Video Graphics Displays, SIM Ports

SOT26



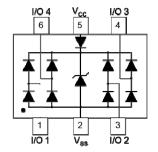
Top View

Features

- IEC 61000-4-2 (ESD): Air ±19kV, Contact ±16kV
- Low Channel Input Capacitance of 0.55pF Max
- ESD Protection for four I/Os and one Vcc
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020 (Lead Free Plating).
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.016 grams (approximate)



Device Schematic

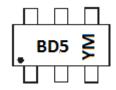
Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT1446-04SO-7	Standard	BD5	7	8	3,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



BD5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	20	13	20	14	20	15	20	16	20	17	20	18
Code	,	4	I	3	(2])	I		I	=
	-		•									
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	a	0	N	D

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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current ,per IEC 61000-4-5	I _{PP_I/O}	4.7	Α	I/O to V _{SS} , 8/20µs
Operating Voltage (DC)	V_{DC}	6	V	V _{CC} to V _{SS}
ESD Protection – Contact Discharge	V _{ESD_I/O}	±16	kV	I/O to V _{SS} , per IEC 61000-4-2
LSD Flotection - Contact Discharge	$V_{ESD}V_{CC}$	±30	kV	V _{CC} to V _{SS} , per IEC 61000-4-2
ESD Protection – Air Discharge, per IEC 61000-4-2	V _{ESD_I/O}	±19	kV	I/O to V _{SS} , per IEC 61000-4-2
Lob i fotestion – All bischarge, per IEC 01000-4-2	$V_{ESD}V_{CC}$	±30	kV	V _{CC} to V _{SS} , per IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P _D	300	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{\theta JA}$	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	VRWM	_	_	5.0	V	V _{CC} to V _{SS}
Reverse Current (Note 6)	I _{R(} V _{CC} to V _{SS)}	_	_	5.0	μA	$V_R = V_{RWM} = 5V$, V_{CC} to V_{SS}
Reverse Current (Note 6)	I _{R(IO} to V _{SS)}	_	_	1.0	μA	$V_R = V_{RWM} = 5V$, any I/O to V_{SS}
Reverse Breakdown Voltage	VBR	6.0	_	9.0	V	I _R = 1mA, V _{CC} to V _{SS}
Forward Clamping Voltage	V _F		0.8	1.0	V	I_F = 15mA, V_{SS} to V_{CC}
Reverse Clamping Voltage (Note 7)	V _{C_I/O}	_	8.5	_	V	I _{PP} =4.7A, I/O to V _{SS} , 8/20μS
ESD Clamping Voltage	V _{ESD} _V _{CC}	_	10	_	V	TLP, 20A, tp = 100 ns, V_{CC} to V_{SS}
ESD Clamping Voltage	V _{ESD} _I/O	_	12	_	V	TLP, 20A, tp = 100 ns, I/O to V _{SS}
Dynamic Resistance	$R_{DIF}V_{CC}$	_	0.14	_	Ω	TLP, 20A, tp = 100 ns, V_{CC} to V_{SS}
Dynamic Resistance	R _{DIF_I/O}	_	0.3	_	Ω	TLP, 20A, tp = 100 ns, I/O to V_{SS}
Channel Input Capacitance	C _{I/O} to V _{SS}	_	0.55	0.65	pF	$V_R = 2.5V$, $V_{CC} = 5V$, $f = 1MHz$
Channel Input Capacitance	C _{I/O} to V _{SS}	_	0.65	_	pF	V _R = 2.5V, V _{CC} = floating, f = 1MHz
Variation of Channel Input Capacitance	C _{I/OMAX} -C _{I/OMIN}	_	0.03	_	pF	$V_{CC} = 5V$, $V_{SS} = 0V$, $I/O = 2.5V$, $f = 1MHz$, $T = +25^{\circ}C$, $C_{I/OMAX} - C_{I/OMIN}$
Variation of Channel Input Capacitance	C _{I/OMAX} -C _{I/OMIN}	_	0.05	_	pF	V_{CC} =floating , V_{SS} = 0V, I/O = 2.5V, f = 1MHz, T = +25°C , $C_{I/OMAX}$ - $C_{I/OMIN}$

Notes:

^{5.} Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

6. Short duration pulse test used to minimize self-heating effect.

7. Clamping voltage value is based on an 8x20µs peak pulse current (I_{pp}) waveform.



0

25

50

75

T_A,AMBIENT TEMPERATURE(°C) Figure 1. Pulse Derating Curve

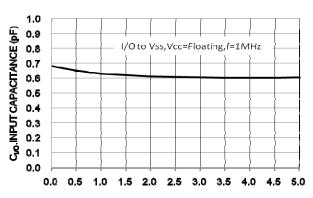
100

125

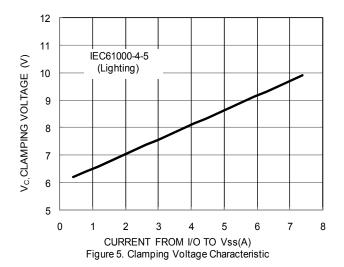
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175

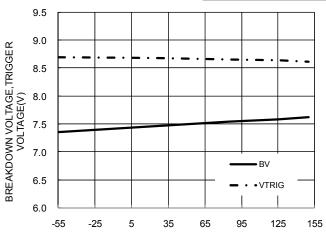
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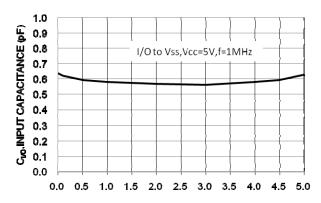
V_M, INPUT VOLTAGE (V) Figure 3. Input Capacitance vs. Input Voltage



DT1446-04SO



T_A, AMBIENT TEMPERATURE (°C) Figure 2. BV, Trigger Voltage vs. Ambient Temperature



V_{I/O,}INPUT VOLTAGE (V) Figure 4. Input Capacitance vs. Input Voltage

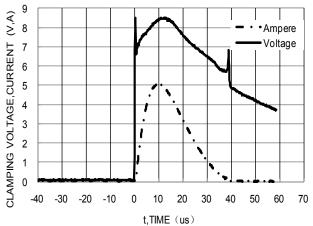
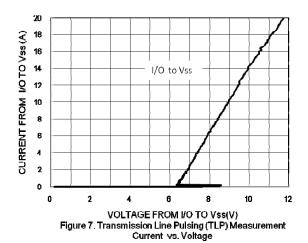
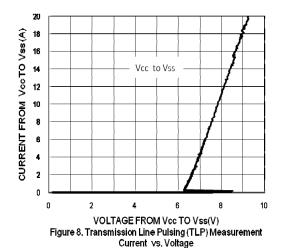


Figure 6. Waveform of Clamping Voltage, Current vs. Time(8/20us, I/O to Vss)

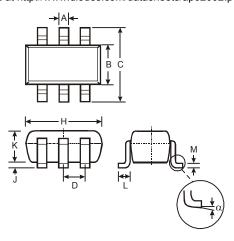






Package Outline Dimensions

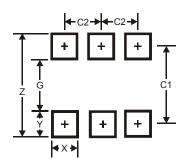
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT26							
Dim	Min	Max	Тур					
Α	0.35	0.50	0.38					
В	1.50	1.70	1.60					
C	2.70	3.00	2.80					
D	_		0.95					
Н	2.90	3.10	3.00					
7	0.013	0.10	0.05					
K	1.00	1.30	1.10					
L	0.35	0.55	0.40					
M	0.10	0.20	0.15					
α	0°	8°	_					
All D	All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95



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